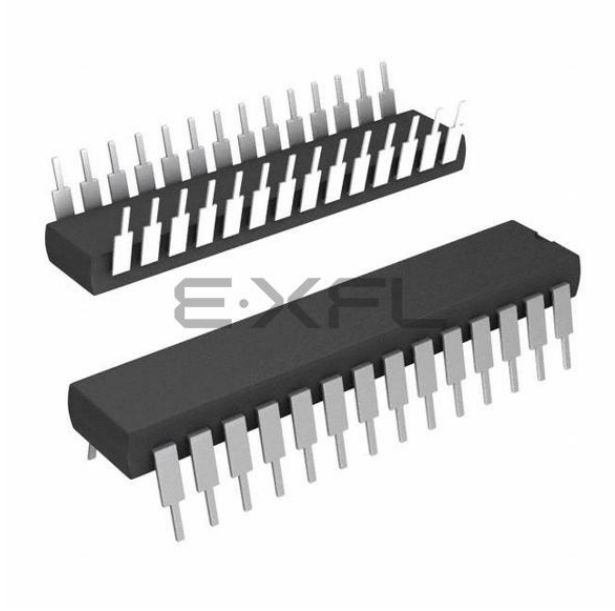

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c72-20e-sp

2.2 Data Memory Organization

The data memory is partitioned into multiple banks which contain the General Purpose Registers and the Special Function Registers. Bits RP1 and RP0 are the bank select bits.

RP1*	RP0

(STATUS<6:5>)

= 00 → Bank0
= 01 → Bank1
= 10 → Bank2 (not implemented)
= 11 → Bank3 (not implemented)

*	Maintain this bit clear to ensure upward compatibility with future products.

Each bank extends up to 7Fh (128 bytes). The lower locations of each bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers, implemented as static RAM.

All implemented banks contain special function registers. Some “high use” special function registers from one bank may be mirrored in another bank for code reduction and quicker access (ex; the STATUS register is in Bank 0 and Bank 1).

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly or indirectly through the File Select Register FSR (Section 2.5).

FIGURE 2-2: REGISTER FILE MAP

File Address	Bank 0	Bank 1	File Address
00h	INDF(1)	INDF(1)	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
7Fh			FFh

Unimplemented data memory locations, read as '0'.
Note 1: Not a physical register.

2.2.2.1 STATUS REGISTER

The STATUS register, shown in Figure 2-3, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

Note 1: These devices do not use bits IRP and RP1 (STATUS<7:6>). Maintain these bits clear to ensure upward compatibility with future products.

Note 2: The C and DC bits operate as a $\overline{borrow}$ and $\overline{digit\ borrow}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

FIGURE 2-3: STATUS REGISTER (ADDRESS 03h, 83h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **IRP**: Register Bank Select bit (used for indirect addressing)
1 = Bank 2, 3 (100h - 1FFh)
0 = Bank 0, 1 (00h - FFh)

bit 6-5: **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h - 1FFh)
`10` = Bank 2 (100h - 17Fh)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes. For devices with only Bank0 and Bank1, the IRP bit is reserved. Always maintain this bit clear.

bit 4: **$\overline{TO}$**: Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred

bit 3: **$\overline{PD}$**: Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction

bit 2: **Z**: Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1: **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for $\overline{borrow}$ the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0: **C**: Carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
1 = A carry-out from the most significant bit of the result occurred
0 = No carry-out from the most significant bit of the result occurred
Note: For $\overline{borrow}$ the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

2.2.2.6 PCON REGISTER

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external $\overline{MCLR}$ Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note:	$\overline{BOR}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}$ is clear, indicating a brown-out has occurred. The $\overline{BOR}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

3.2 PORTB and the TRISB Register

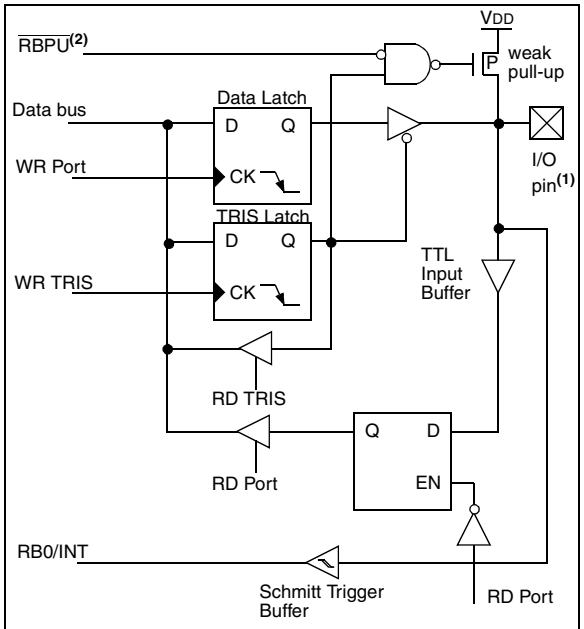
PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (=1) will make the corresponding PORTB pin an input, i.e., put the corresponding output driver in a hi-impedance mode. Clearing a TRISB bit (=0) will make the corresponding PORTB pin an output, i.e., put the contents of the output latch on the selected pin.

EXAMPLE 3-1: INITIALIZING PORTB

```
BCF    STATUS, RP0  ;
CLRF   PORTB        ; Initialize PORTB by
                    ; clearing output
                    ; data latches
BSF    STATUS, RP0  ; Select Bank 1
MOVLW  0xCF         ; Value used to
                    ; initialize data
                    ; direction
MOVWF  TRISB        ; Set RB<3:0> as inputs
                    ; RB<5:4> as outputs
                    ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 3-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION<7>).

Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

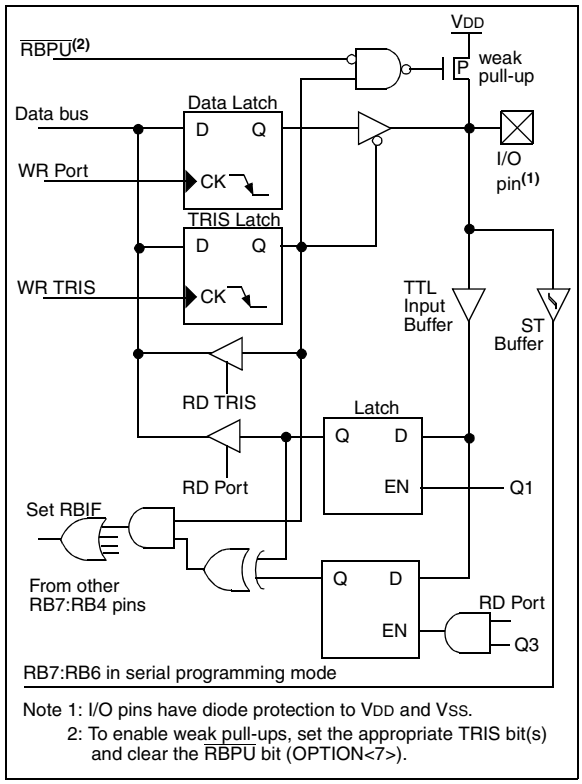
This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 3-4: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.
2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION<7>).

5.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
  (Two 8-bit registers; TMR1H and TMR1L)
- Readable and writable (Both registers)
- Internal or external clock select
- Interrupt on overflow from FFFFh to 0000h
- Reset from CCP module trigger

Timer1 has a control register, shown in Figure 5-1. Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Figure 5-2 is a simplified block diagram of the Timer1 module.

Additional information on timer modules is available in the PIC® Mid-Range MCU Reference Manual, DS33023.

5.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RC1/T1OSI and RC0/T1OSO/T1CKI pins become inputs. That is, the TRISC<1:0> value is ignored.

Timer1 also has an internal “reset input”. This reset can be generated by the CCP module (Section 7.0).

FIGURE 5-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3: **T1OSCEN**: Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut off
Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain

bit 2: **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit

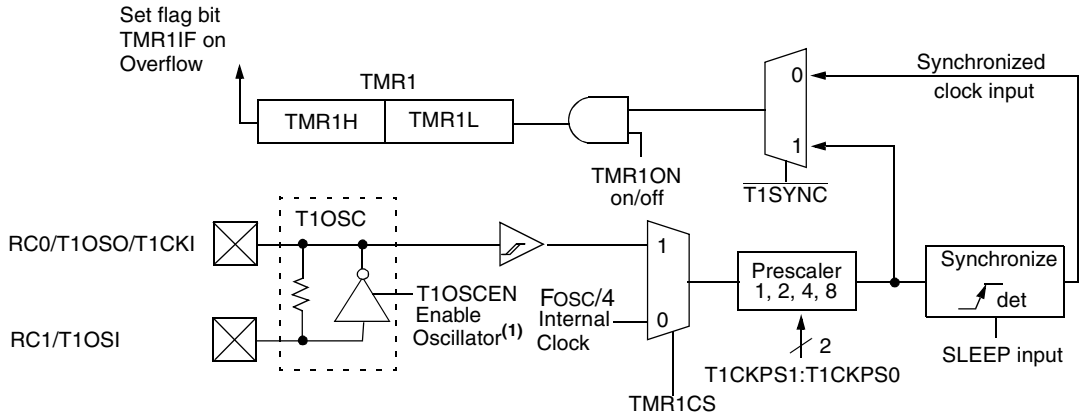
TMR1CS = 1
1 = Do not synchronize external clock input
0 = Synchronize external clock input

TMR1CS = 0
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1: **TMR1CS**: Timer1 Clock Source Select bit
1 = External clock from pin RC0/T1OSO/T1CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0: **TMR1ON**: Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

FIGURE 5-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

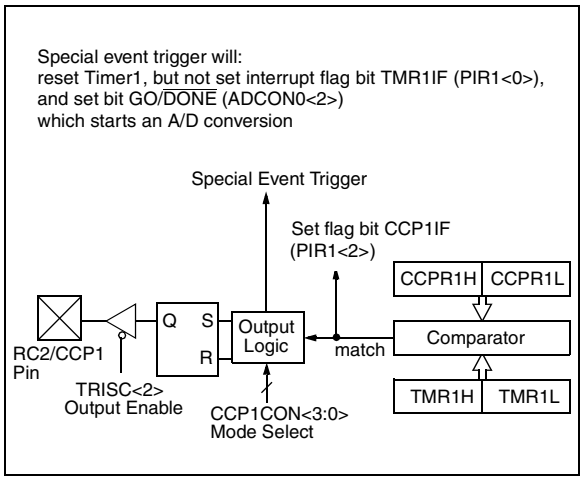
7.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RC2/CCP1 pin is:

- driven High
- driven Low
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit CCP1IF is set.

FIGURE 7-3: COMPARE MODE OPERATION BLOCK DIAGRAM



7.2.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

Note:	Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the data latch.

7.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

7.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

7.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special trigger output of CCP1 resets the TMR1 register pair, and starts an A/D conversion (if the A/D module is enabled).

Note:	The special event trigger from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

TABLE 7-2 REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by Capture and Timer1.
Note 1: These bits/registers are unimplemented, read as '0'.

For an example PWM period and duty cycle calculation, see the PIC® Mid-Range MCU Reference Manual (DS33023).

7.3.3 SET-UP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
3. Make the CCP1 pin an output by clearing the TRISC<2> bit.
4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
5. Configure the CCP1 module for PWM operation.

TABLE 7-3 EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 20 MHz

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

TABLE 7-4 REGISTERS ASSOCIATED WITH PWM AND TIMER2

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.
Note 1: These bits/registers are unimplemented, read as '0'.

8.3 SPI Mode for PIC16CR72

This section contains register definitions and operational characteristics of the SPI module on the PIC16CR72 device only.

Additional information on SPI operation may be found in the PIC® Mid-Range MCU Reference Manual, DS33023.

FIGURE 8-4: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS 94h) (PIC16CR72)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n =Value at POR reset

bit 7: **SMP:** SPI data input sample phase
SPI Master Operation
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave Mode
SMP must be cleared when SPI is used in slave mode

bit 6: **CKE**: SPI Clock Edge Select
CKP = 0
1 = Data transmitted on rising edge of SCK
0 = Data transmitted on falling edge of SCK
CKP = 1
1 = Data transmitted on falling edge of SCK
0 = Data transmitted on rising edge of SCK

bit 5: **D/$\overline{A}$**: Data/$\overline{Address}$ bit (I^2C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4: **P**: Stop bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Start bit is detected last, SSPEN is cleared)
1 = Indicates that a stop bit has been detected last (this bit is '0' on RESET)
0 = Stop bit was not detected last

bit 3: **S**: Start bit (I^2C mode only. This bit is cleared when the SSP module is disabled, or when the Stop bit is detected last, SSPEN is cleared)
1 = Indicates that a start bit has been detected last (this bit is '0' on RESET)
0 = Start bit was not detected last

bit 2: **R/$\overline{W}$**: Read/Write bit information (I^2C mode only)
This bit holds the R/W bit information following the last address match. This bit is only valid from the address match to the next start bit, stop bit, or $\overline{ACK}$ bit.
1 = Read
0 = Write

bit 1: **UA**: Update Address (10-bit I^2C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

bit 0: **BF**: Buffer Full Status bit

Receive (SPI and I^2C modes)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Transmit (I^2C mode only)
1 = Transmit in progress, SSPBUF is full
0 = Transmit complete, SSPBUF is empty

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) RC5/SDO
- Serial Data In (SDI) RC4/SDI/SDA
- Serial Clock (SCK) RC3/SCK/SCL

Additionally a fourth pin may be used when in a slave mode of operation:

- Slave Select ($\overline{SS}$) RA5/$\overline{SS}$/AN4

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master Operation (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Clock Edge (Output data on rising/falling edge of SCK)
- Clock Rate (master operation only)
- Slave Select Mode (Slave mode only)

To enable the serial port, SSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON register, and then set bit SSPEN. This configures the SDI, SDO, SCK, and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRISC register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (master operation) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- $\overline{SS}$ must have TRISA<5> set

Note:	When the SPI is in Slave Mode with $\overline{SS}$ pin control enabled, (SSPCON<3:0> = 0100) the SPI module will reset if the $\overline{SS}$ pin is set to V_{DD}.
Note:	If the SPI is used in Slave Mode with CKE = '1', then the $\overline{SS}$ pin control must be enabled.

FIGURE 8-6: SSP BLOCK DIAGRAM (SPI MODE)(PIC16CR72)

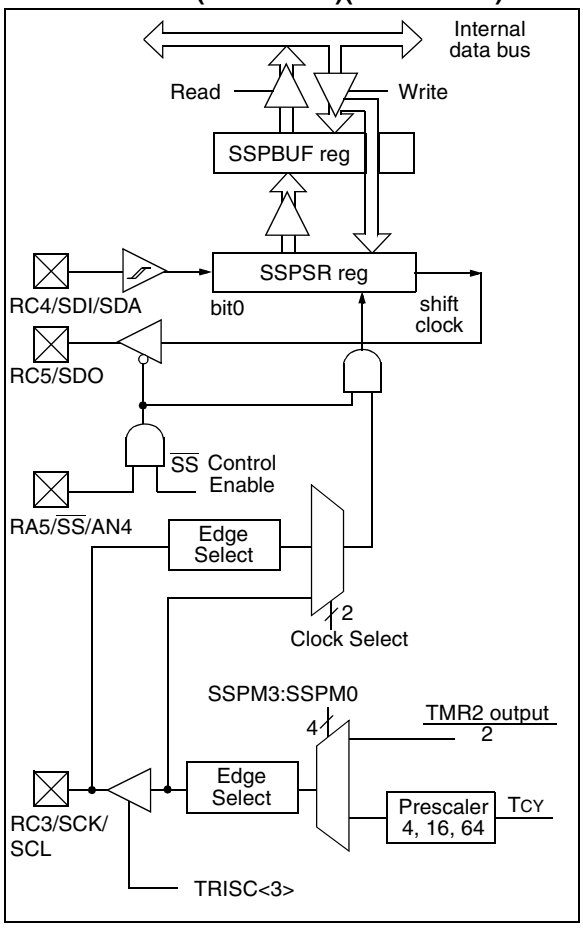
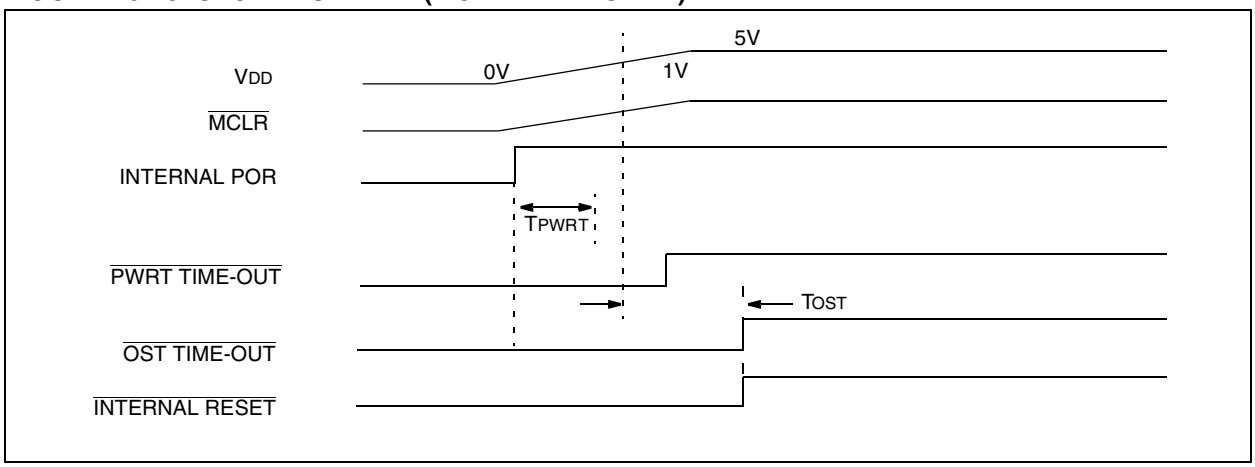


TABLE 8-2 REGISTERS ASSOCIATED WITH SPI OPERATION (PIC16CR72)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
94h	SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the SSP in SPI mode.
Note 1: Always maintain these bits clear.

FIGURE 10-10: SLOW RISE TIME ($\overline{MCLR}$ TIED TO V_{DD})



13.1 DC Characteristics: PIC16C72/CR72-04 (Commercial, Industrial, Extended) PIC16C72/CR72-10 (Commercial, Industrial, Extended) PIC16C72/CR72-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial

Param No.	Characteristic	Sym	PIC16C72			PIC16CR72			Units	Conditions
			Min	Typ†	Max	Min	Typ†	Max		
D001	Supply Voltage	VDD	4.0	-	**6.0**	4.0	-	**5.5**	V	XT, RC and LP osc
D001A			4.5	-	5.5	4.5	-	5.5	V	HS osc
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	3.7	4.0	4.4	V	Extended Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5.0	-	2.7	5.0	mA	XT, RC osc FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	-	10	20	mA	HS osc FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	-	1.5	16	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	-	1.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	-	2.5	19	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

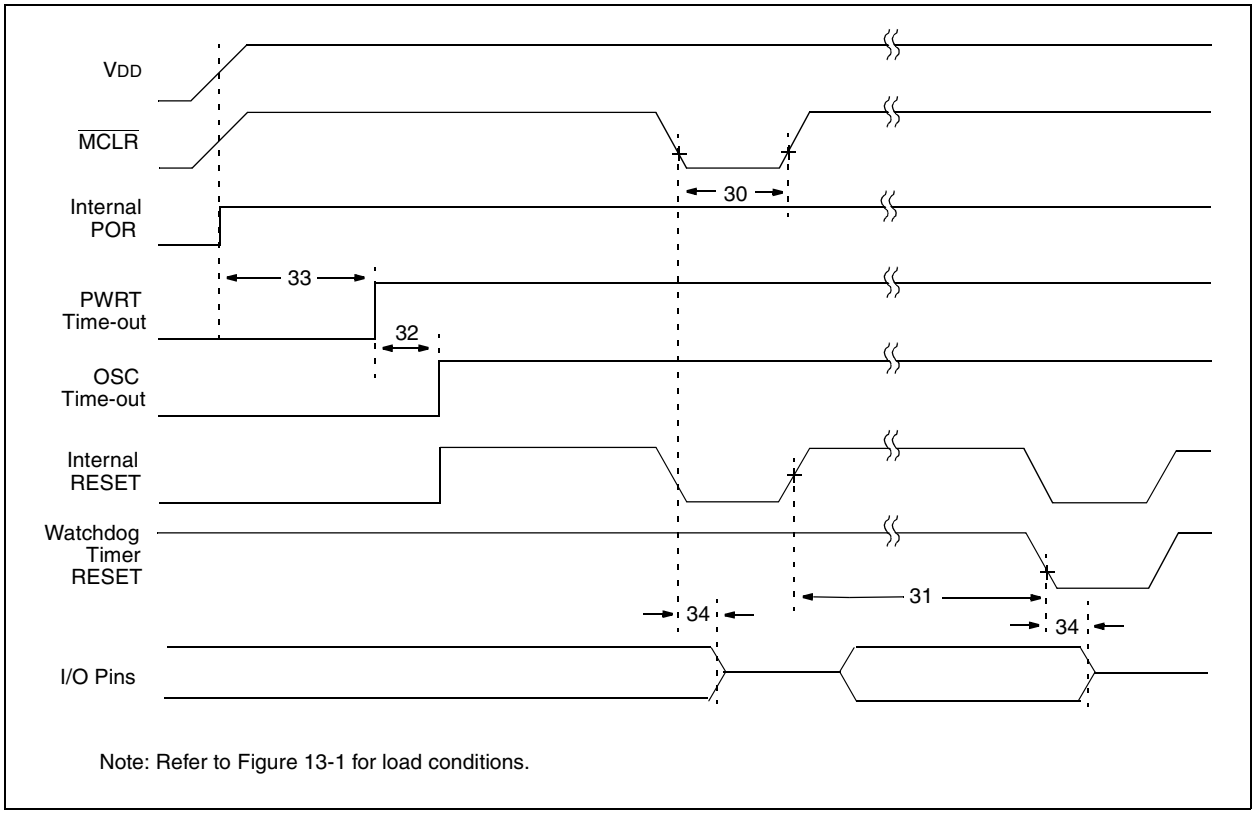
Note 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

Note 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

Note 5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Note 6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

FIGURE 13-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 13-1 for load conditions.

FIGURE 13-5: BROWN-OUT RESET TIMING

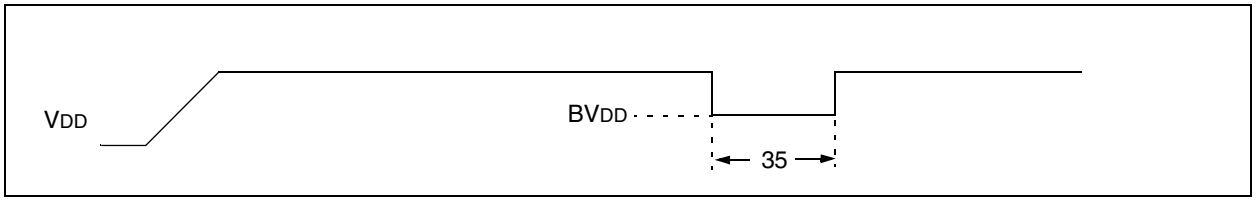


TABLE 13-5 RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—	—	µs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.1	µs	
35	TBOR	Brown-out Reset pulse width	100	—	—	µs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 13-8 SPI SLAVE MODE REQUIREMENTS (CKE=0) - PIC16C72

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70	TssL2scH, TssL2scL	SS↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75	TdoR	SDO data output rise time	—	10	25	ns	
76	TdoF	SDO data output fall time	—	10	25	ns	
77	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance	10	—	50	ns	
78	TscR	SCK output rise time (master mode)	—	10	25	ns	
79	TscF	SCK output fall time (master mode)	—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

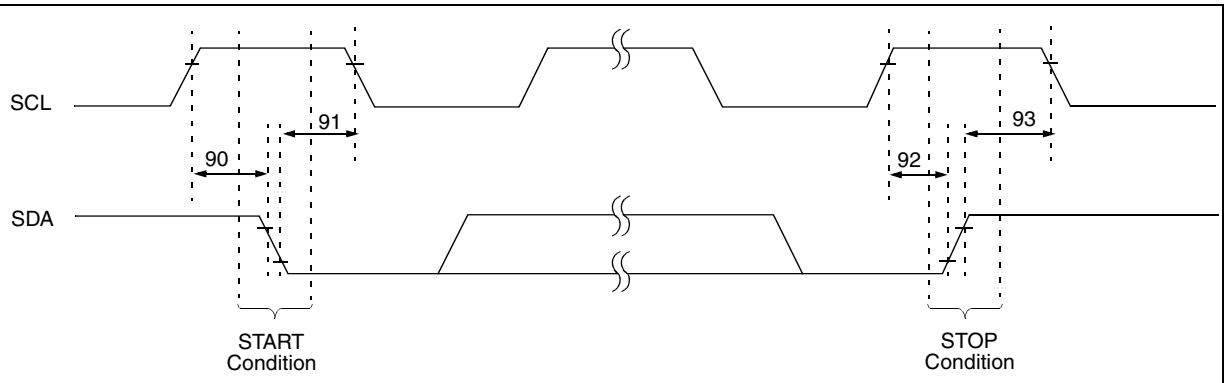
TABLE 13-9 SPI MODE REQUIREMENTS - PIC16CR72

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	TCY	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}$↓ edge	—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge	1.5TCY + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-12: I^2C BUS START/STOP BITS TIMING



Note: Refer to Figure 13-1 for load conditions

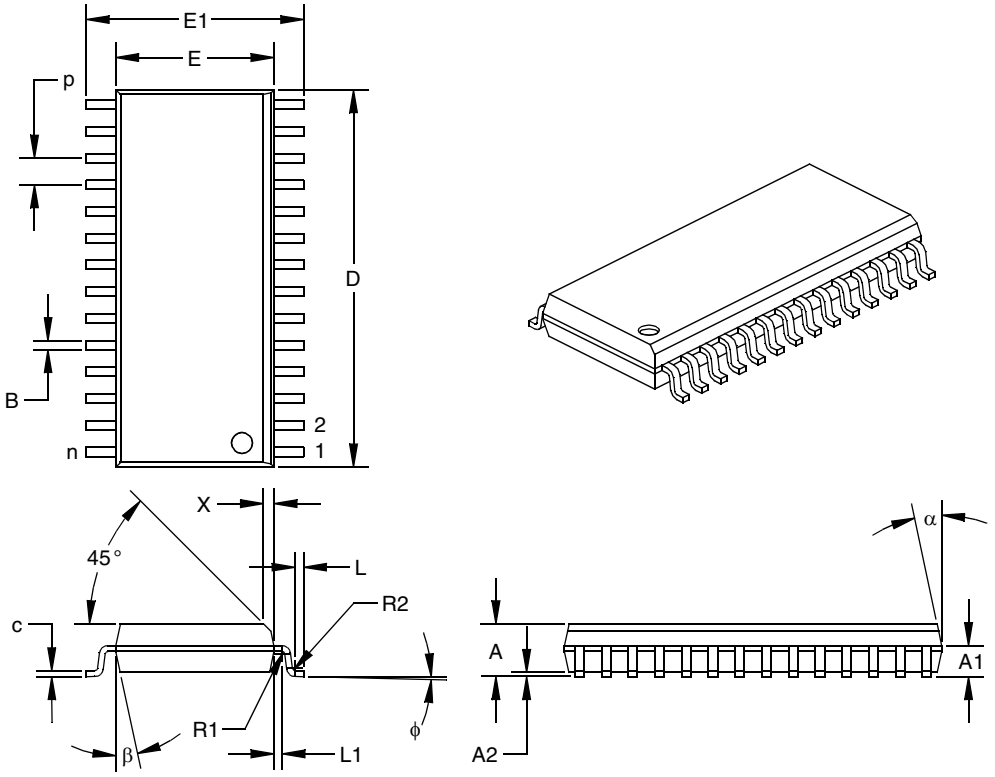
TABLE 13-10 I^2C BUS START/STOP BITS REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ	Max	Units	Conditions
90	TSU:STA	START condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for repeated START condition
			400 kHz mode	600	—	—		
91	THD:STA	START condition Hold time	100 kHz mode	4000	—	—	ns	After this period the first clock pulse is generated
			400 kHz mode	600	—	—		
92	TSU:STO	STOP condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
93	THD:STO	STOP condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

NOTES:

16.4 28-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	p		0.050			1.27	
Number of Pins	n		28			28	
Overall Pack. Height	A	0.093	0.099	0.104	2.36	2.50	2.64
Shoulder Height	A1	0.048	0.058	0.068	1.22	1.47	1.73
Standoff	A2	0.004	0.008	0.011	0.10	0.19	0.28
Molded Package Length	D‡	0.700	0.706	0.712	17.78	17.93	18.08
Molded Package Width	E‡	0.292	0.296	0.299	7.42	7.51	7.59
Outside Dimension	E1	0.394	0.407	0.419	10.01	10.33	10.64
Chamfer Distance	X	0.010	0.020	0.029	0.25	0.50	0.74
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.011	0.016	0.021	0.28	0.41	0.53
Foot Angle	ϕ	0	4	8	0	4	8
Radius Centerline	L1	0.010	0.015	0.020	0.25	0.38	0.51
Lead Thickness	c	0.009	0.011	0.012	0.23	0.27	0.30
Lower Lead Width	B†	0.014	0.017	0.019	0.36	0.42	0.48
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter.

† Dimension “B” does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003” (0.076 mm) per side or 0.006” (0.152 mm) more than dimension “B.”

‡ Dimensions “D” and “E” do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010” (0.254 mm) per side or 0.020” (0.508 mm) more than dimensions “D” or “E.”

NOTES:

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